PC352

■ Features

1. Opaque type, mini-flat package **PC352** (1-channel)

- 2. High resistance to noise due to high common mode rejection voltage (Vcm: TYP. 1.5kV)
- 3. Subminiature type (The volume is smaller than that of our conventional DIP type by as far as 30%.)
- 4. Isolatin voltage between input and output **PC352•••**Viso(rms): 3.75kV
- 5. Recognized by UL, file No. E64380
- * Employs double transfer mold technology

■ Applications

1. Programmable controllers

■ Package Specifications

Model No.	Package specification			
PC352N	Taping reel diameter 370mm (3 000 pcs)			
PC352NT	Taping reel diameter 178mm (750 pcs)			

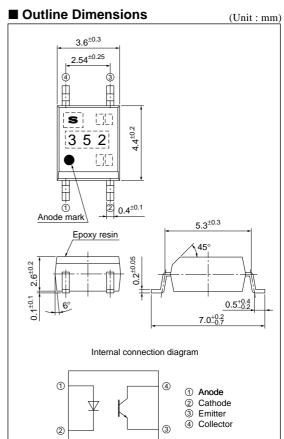
■ Absolute Maximum Ratings

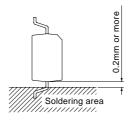
(Ta=25°C)

				(1u=25 C)	
Parameter		Symbol	Rating	Unit	
Input	*1 Forward current	IF	50	mA	
	*2 Peak forward current	IFM	1	A	
	Reverse voltage	VR	6	V	
	*1 Power dissipation	P	70	mW	
Output	*1 Collector-emitter voltage	Vceo	35	V	
	Emitter-collector voltage	VECO	6	V	
	Collector current	Ic	50	mA	
	*1 Collector dissipation	Pc	150	mW	
*1 Total power dissipation		Ptot	170	mW	
Operating temperature		Topr	-30 to +100	°C	
Storage temperature		Tstg	-40 to +125	°C	
*3 Isolation voltage		V _{iso} (rms)	3.75	kV	
*4 Soldering temperature		Tsol	260	°C	

^{*1} The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig.2 to 5
*2 Pulse width≤100µs, Duty ratio:0.01, Refer to Fig.6

Opaque*, Mini-flat Package, **High Resistance to Noise Type Photocoupler**





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Internet address for Electronic Components Group http://www.sharp.co.jp/ecg/

^{*3} AC for 1min., 40 to 60% RH, f=60Hz *4 For 10s

■ Electro-optical Characteristics

(Ta=25°C)

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Forward voltage		V _F	I _F =20mA	_	1.2	1.4	V
Input	Reverse current		IR	$V_R = 4V$	_	_	10	μA
	Terminal capacitance		Ct	V = 0, $f = 1kHz$	_	30	200	pF
Output	Collector dark current		Iceo	$V_{CE}=20V$, $I_F=0$	_	_	100	nA
	Collector-emitter breakdown voltage		BVCEO	Ic=0.1mA, I _F =0	35	-	_	V
	Emitter-collector breakdown voltage		BVECO	$I_E = 10 \mu A, I_F = 0$	6	_	_	V
Transfer charac- teristics	Collector current		Ic	$I_F=5mA$, $V_{CE}=5V$	4.5	_	24	mA
	Collector-emitter saturation voltage		V _{CE(sat)}	I _F =20mA, I _C =1mA	_	0.1	0.2	V
	Isolation resistance		Riso	DC500V 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	_	Ω
	Floating capacitance		Cf	V = 0, $f = 1MHz$	_	0.6	1.0	pF
	Cut-off frequency		fc	V_{CE} =5 V , I_{C} =2 mA R_{L} =100 Ω , -3 dB	15	80	_	
	Response time	Rise time	tr	$V_{CE}=2V$, $I_{C}=2mA$	_	4	18	μs
		Fall time	tf	$R_L=100\Omega$	_	5	20	μs
	*5 Common mode rejection voltage		CMR	$ I_F = 0, R_L = 470\Omega $ $ V_{ND} = 100 mV $ $ V_{CM} = 1.5 kV(peak) $	10	_	_	kV/μs

^{*5} Refer to Fig.1

Fig.1 Test Circuit for Common Mode Rejection Voltage

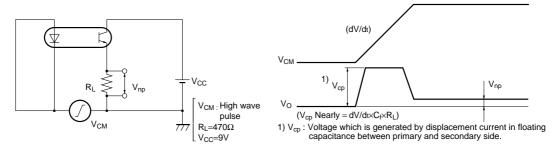


Fig.2 Forward Current vs. Ambient Temperature

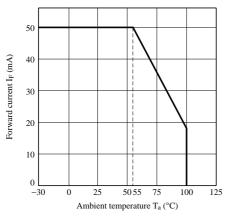


Fig.4 Collector Power Dissipation vs. Ambient Temperature

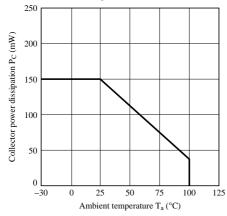


Fig.6 Peak Forward Current vs. Duty Ratio

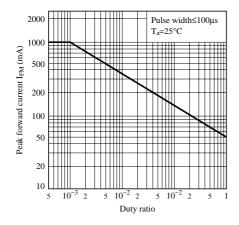


Fig.3 Diode Power Dissipation vs. Ambient Temperature

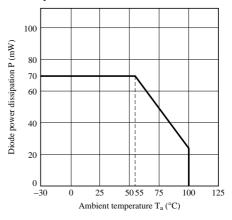


Fig.5 Total Power Dissipation vs. Ambient Temperature

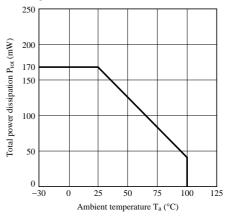


Fig.7 Forward Current vs. Forward Voltage

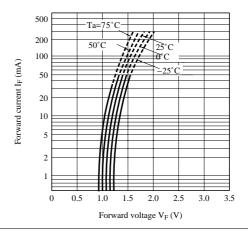


Fig.8 Current Transfer Ratio vs. Forward Current

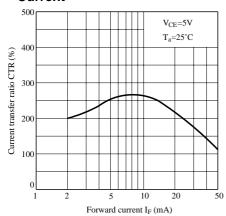


Fig.10 Relative Current Transfer Ratio vs.
Ambient Temperature

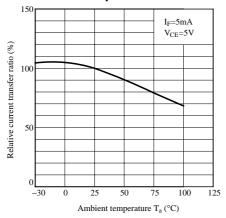


Fig.12 Collector Dark Current vs. Ambient Temperature

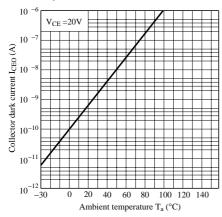


Fig.9 Collector Current vs. Collector-emitter Voltage

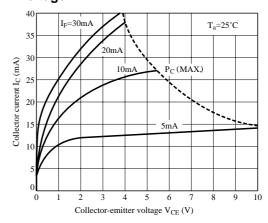


Fig.11 Collector-emitter Saturation Voltage vs. Ambient Temperature

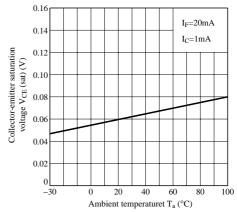


Fig.13 Response Time vs. Load Resistance

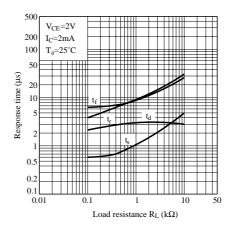


Fig.14 Test Circuit for Response Time

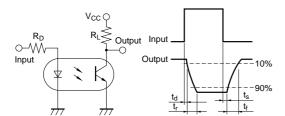


Fig.15 Voltage Gain vs Frequency

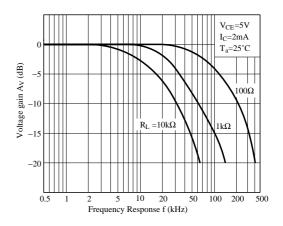


Fig.16 Collector-emitter Saturation Voltage vs. Forward Current

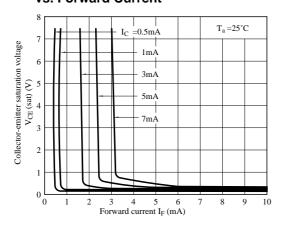
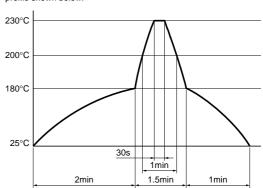


Fig.17 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



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